

ABSTRACT OF THE DISCLOSURE

A pad structure of semiconductor device have a special via pattern to divide the IMD layer into separated IMD blocks, so that the wire bonding cracks are reduced or completely inhibited. According to the invention, the pad structure with a single via pattern of the invention does effectively reduce the wire bonding cracks, and the pad structure with two layers of special via patterns of the invention does completely inhibit the wire bonding cracks.

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